

AMENDMENTS TO THE CLAIMS

1. (Currently amended) A manufacturing method for a multilayer ceramic substrate, comprising

providing an unsintered composite laminate comprising a sintered plate of fired first ceramic functional material, a plurality of green layers for the substrate which comprise a second ceramic functional material which is different from said first ceramic functional material, [[a]] at least one of the plurality of green layers having a cavity, at least one restriction layer are arranged so as to contact a primary face of at least one of said green layers for the substrate and which comprises a sintering-resistant material which does not sinter at the sintering temperature of said second ceramic functional material, and at least one wiring conductor associated with a green layer for the substrate, wherein said sintered plate of fired first ceramic functional material is disposed in said cavity and is arranged so as to extend along a primary face of a green layer for substrate and in substantially parallel planes which are substantially perpendicular to the lamination direction of said unsintered composite laminate, said sintered plate has an area smaller than the area of the primary face of the green layer for the substrate on which it is arranged, and said sintered plate has a thickness which is less than the green layer having a cavity ~~on~~ within which it is arranged, and wherein a cavity having a sintered plate therein has a maximum thickness which does not exceed the thickness of the green layer containing that cavity and any via hole communicating with said cavity having a sintered plate therein has an area in said plane smaller than the area of the sintered plate in said plane in that cavity; and

firing said unsintered composite laminate at a temperature at which said second ceramic functional material is sintered.

2-3 (Cancelled).

4. (Previously presented) A manufacturing method for a multilayer ceramic substrate according to Claim 1, wherein the sintered plate has a thickness which is less than the thickness of said cavity.

5. (Original) A manufacturing method for a multilayer ceramic substrate according to Claim 1, wherein an external surface of said sintered plate has a terminal electrode thereon, and said wiring conductor is in electrical connect with said terminal electrode.

6. (Original) A manufacturing method for a multilayer ceramic substrate according to Claim 5, wherein said sintered plate is a capacitor element, an inductor element or a resistor element.

7. (Original) A manufacturing method for a multilayer ceramic substrate according to Claim 5, wherein said sintered plate comprises a laminate of a plurality of layers comprising said first ceramic functional material and has an internal conductor between a pair of adjacent layers thereof.

8. (Original) A manufacturing method for a multilayer ceramic substrate according to Claim 1, wherein said sintered plate has a thickness of about 100 μm or less.

9. (Original) A manufacturing method for a multilayer ceramic substrate according to Claim 1, wherein said unsintered composite laminate is fired at a temperature of about 1,000°C or less.

10. (Original) A manufacturing method for a multilayer ceramic substrate according to Claim 1, wherein said first ceramic functional material has a sintering temperature higher than the firing temperature employed in firing said unsintered composite laminate.

11. (Original) A manufacturing method for a multilayer ceramic substrate according to Claim 1, wherein two said restriction layers are present in said unsintered composite laminate and are arranged so as to be located at both ends in the direction of lamination of said unsintered composite laminate.

12. (Original) A manufacturing method for a multilayer ceramic substrate according to Claim 11, further comprising a step of removing said restriction layers after the firing of said unsintered composite laminate.

13. (Original) A manufacturing method for a multilayer ceramic substrate according to Claim 12, wherein said sintered plate has a thickness of about 100 μm or less, said unsintered composite laminate is fired at a temperature of about 1,000°C or less, and wherein said first ceramic functional material has a sintering temperature

higher than the firing temperature employed in firing said unsintered composite laminate.

14. (Original) A manufacturing method for a multilayer ceramic substrate according to Claim 1, wherein the green layers for the substrate comprise glass.

15. (Original) A manufacturing method for a multilayer ceramic substrate according to Claim 13, wherein the green layers for the substrate comprise a combination of ceramic insulation material and glass in which the glass is at least about 5 weight percent of the combination.

16. (Original) A manufacturing method for a multilayer ceramic substrate according to Claim 1, further comprising producing said unsintered composite laminate.

17. (Original) A manufacturing method for a multilayer ceramic substrate according to Claim 15, further comprising producing said sintered plate of fired first ceramic functional material.

18. (Original) A manufacturing method for a multilayer ceramic substrate according to Claim 1, further comprising producing said sintered plate of fired first ceramic functional material.

19. (Original) A manufacturing method for a multilayer ceramic substrate according to Claim 1, wherein said unsintered composite laminate has a plurality of said sintered plates each of which is arranged so as to extend along a primary face of a green layer for substrate and each of which is individually selected from the group consisting of a capacitor element, an inductor element and a resistor element.

20. (Original) A multilayer ceramic substrate produced by a manufacturing method according to Claim 1.